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ON Semiconductor®

# FDB0690N1507L

# N-Channel PowerTrench® MOSFET

### **150 V, 115 A, 6.9 m** $\Omega$ **Features**

- Max  $r_{DS(on)}$  = 6.9 m $\Omega$  at  $V_{GS}$  = 10 V,  $I_D$  = 17 A
- Fast Switching Speed
- Low Gate Charge
- High Performance Trench Technology for Extremely Low R<sub>DS(on)</sub>
- High Power and Current Handling Capability
- RoHS Compliant



# **General Description**

N-Channel MOSFET is produced Semiconductor's advance PowerTrench® process that has been especially tailored to minimize the on-state resistance while maintaining superior ruggedness and switching performance for industrial applications.

D(Pin4, tab)

S(Pin2,3,5,6,7)

### **Applications**

- Industrial Motor Drive
- Industrial Power Supply
- Industrial Automation
- Battery Operated tools
- Battery Protection
- Solar Inverters
- UPS and Energy Inverters

G

- Energy Storage
- Load Switch



# **MOSFET Maximum Ratings** T<sub>C</sub> = 25 °C unless otherwise noted.

Symbol	Parame	ter		Ratings	Units
$V_{DS}$	Drain to Source Voltage			150	V
$V_{GS}$	Gate to Source Voltage			±20	V
I <sub>D</sub>	Drain Current -Continuous	T <sub>C</sub> = 25°C	(Note 5)	115	
	-Continuous	-Continuous $T_C = 100$ °C		81	Α
	-Pulsed		(Note 4)	636	
E <sub>AS</sub>	Single Pulse Avalanche Energy		(Note 3)	633	mJ
P <sub>D</sub>	Power Dissipation	T <sub>C</sub> = 25°C		250	W
	Power Dissipation	T <sub>A</sub> = 25°C	(Note 1a)	3.8	VV
T <sub>J</sub> , T <sub>STG</sub>	Operating and Storage Junction Temperation	ture Range		-55 to +175	°C

#### **Thermal Characteristics**

$R_{\theta JC}$	Thermal Resistance, Junction to Case	(Note 1)	0.6	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient	(Note 1a)	40	C/VV

### **Package Marking and Ordering Information**

Device Marking	Device	Package	Reel Size	Tape Width	Quantity
FDB0690N1507L	FDB0690N1507L	D2-PAK-7L	330 mm	24 mm	800 units

# **Electrical Characteristics** T<sub>J</sub> = 25 °C unless otherwise noted.

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Units
Off Chara	cteristics					
$BV_{DSS}$	Drain to Source Breakdown Voltage	$I_D = 250 \mu A, V_{GS} = 0 V$	150			V
$\frac{\Delta BV_{DSS}}{\Delta T_{J}}$	Breakdown Voltage Temperature Coefficient	$I_D$ = 250 $\mu$ A, referenced to 25 °C		106		mV/°C
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	V <sub>DS</sub> = 120 V, V <sub>GS</sub> = 0 V			1	μΑ
I <sub>GSS</sub>	Gate to Source Leakage Current	$V_{GS} = \pm 20 \text{ V}, V_{DS} = 0 \text{ V}$			±100	nA

### On Characteristics (Note 2)

$V_{GS(th)}$	Gate to Source Threshold Voltage	$V_{GS} = V_{DS}, I_{D} = 250 \mu A$	2	3.3	4	V
$\frac{\Delta V_{GS(th)}}{\Delta T_J}$	Gate to Source Threshold Voltage Temperature Coefficient	$I_D$ = 250 $\mu$ A, referenced to 25 °C		-13		mV/°C
r	Static Drain to Source On Resistance	V <sub>GS</sub> = 10 V, I <sub>D</sub> = 17 A		5.4	6.9	mΩ
r <sub>DS(on)</sub>	Static Drain to Source On Resistance	$V_{GS}$ = 10 V, $I_D$ = 17 A, $T_J$ = 150°C		12.9	16.5	1115.2
9 <sub>FS</sub>	Forward Transconductance	V <sub>DS</sub> = 10 V, I <sub>D</sub> = 17 A		60		S

### **Dynamic Characteristics**

C <sub>iss</sub>	Input Capacitance	V <sub>DS</sub> = 75 V, V <sub>GS</sub> = 0 V, f = 1 MHz	6265	8775	pF
C <sub>oss</sub>	Output Capacitance		502	705	pF
C <sub>rss</sub>	Reverse Transfer Capacitance		25	40	pF
$R_g$	Gate Resistance		2.5		Ω

# **Switching Characteristics**

t <sub>d(on)</sub>	Turn-On Delay Time		35	56	ns
t <sub>r</sub>	Rise Time	V <sub>DD</sub> = 75 V, I <sub>D</sub> = 17 A,	30	48	ns
t <sub>d(off)</sub>	Turn-Off Delay Time	$V_{GS}$ = 10 V, $R_{GEN}$ = 6 $\Omega$	53	85	ns
t <sub>f</sub>	Fall Time		14	25	ns
Qg	Total Gate Charge	V 75 V L 47 A	82	115	nC
Q <sub>gs</sub>	Gate to Source Gate Charge	V <sub>DD</sub> = 75 V, I <sub>D</sub> = 17 A, V <sub>GS</sub> = 10 V	29		nC
Q <sub>gd</sub>	Gate to Drain "Miller" Charge	vgs 10 v	15		nC

### **Drain-Source Diode Characteristics**

I <sub>S</sub>	Maximum Continuous Drain to Source Diode Forward Current			-	-	115	Α
I <sub>SM</sub>	Maximum Pulsed Drain to Source Diode Forward Current			-	-	636	Α
$V_{SD}$	Source to Drain Diode Forward Voltage	$V_{GS} = 0 \text{ V}, I_S = 17 \text{ A}$ (	Note 2)		0.8	1.2	V
t <sub>rr</sub>	Reverse Recovery Time	-I <sub>F</sub> = 17 A, di/dt = 100 A/μs			106	170	ns
Q <sub>rr</sub>	Reverse Recovery Charge				226	362	nC

#### Notes:

- 2. Pulse Test: Pulse Width < 300  $\mu s,$  Duty cycle < 2.0 %.
- 3. EAs of 633 mJ is based on starting  $T_J = 25~^{\circ}C$ , L = 0.3 mH,  $I_{AS} = 65$  A,  $V_{DD} = 135$  V,  $V_{GS} = 10$  V. 100% test at L = 0.1 mH,  $I_{AS} = 94$  A.
- 4. Pulsed Id please refer to Figure "Forward Bias Safe Operating Area" for more details.
- 5. Computed continuous current limited to Max Junction Temperature only, actual continuous current will be limited by thermal & electro-mechanical application board design.

 $R_{0,C}$  is the sum of the junction-to-case and case-to-ambient thermal resistance where the case thermal reference is defined as the solder mounting surface of the drain pins.  $R_{0,C}$  is guaranteed by design while  $R_{0,CA}$  is determined by the user's board design.

a) 40 °C/W when mounted on a 1 in  $^2$  pad of 2 oz copper. b) 62.5 °C/W when mounted on a minimum pad of 2 oz copper.

### Typical Characteristics T<sub>J</sub> = 25 °C unless otherwise noted.

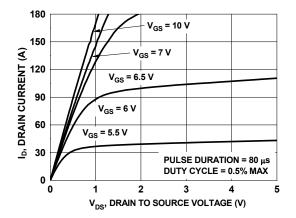


Figure 1. On Region Characteristics

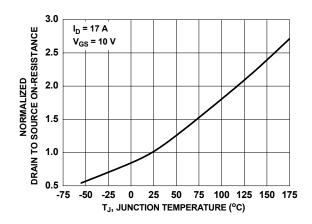


Figure 3. Normalized On Resistance vs. Junction Temperature

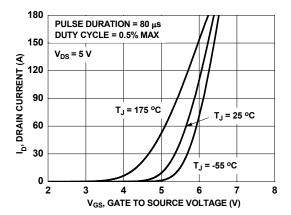


Figure 5. Transfer Characteristics

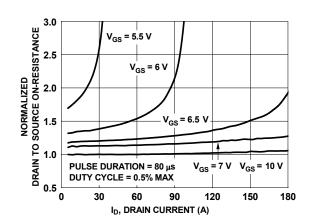


Figure 2. Normalized On-Resistance vs. Drain Current and Gate Voltage

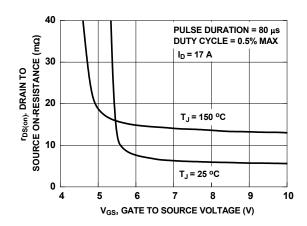


Figure 4. On-Resistance vs. Gate to Source Voltage

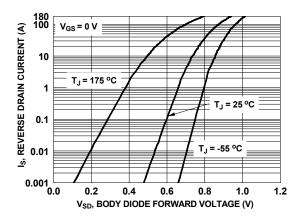


Figure 6. Source to Drain Diode Forward Voltage vs. Source Current

# **Typical Characteristics** $T_J = 25$ °C unless otherwise noted.

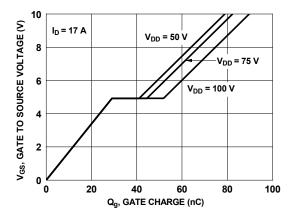


Figure 7. Gate Charge Characteristics

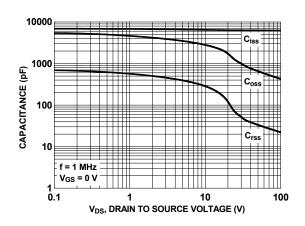


Figure 8. Capacitance vs. Drain to Source Voltage

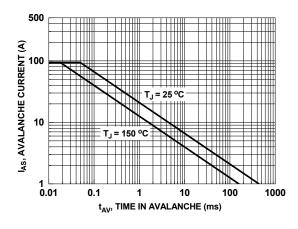


Figure 9. Unclamped Inductive Switching Capability

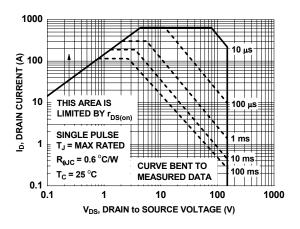


Figure 10. Forward Bias Safe Operating Area

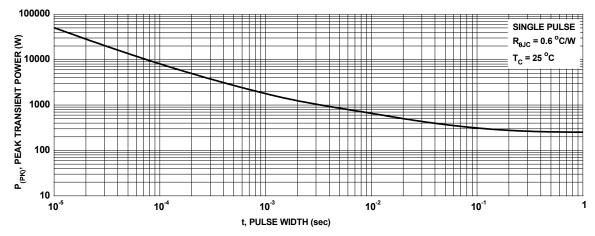


Figure 11. Single Pulse Maximum Power Dissipation



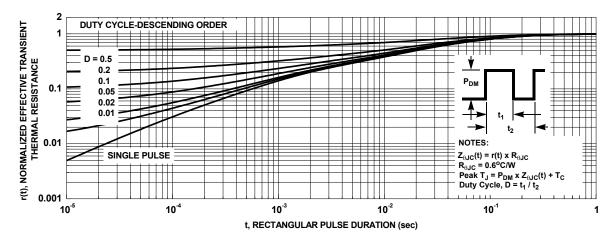


Figure 12. Junction-to-Case Transient Thermal Response Curve

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